

L Number	Hits	Search Text	DB	Time stamp
1	0	grind with semiconductor same mirror and bump\$	USPAT; US-PPGPUB; EPO; JPO USPAT; US-PPGPUB; EPO; JPO USPAT; US-PPGPUB; EPO; JPO USPAT; US-PPGPUB; EPO; JPO	2004/06/04 18:33
2	884	semiconductor same mirror and bump\$	USPAT; US-PPGPUB; EPO; JPO USPAT; US-PPGPUB; EPO; JPO USPAT; US-PPGPUB; EPO; JPO USPAT; US-PPGPUB; EPO; JPO	2004/06/04 18:33
3	194	semiconductor same mirror same bump\$	USPAT; US-PPGPUB; EPO; JPO USPAT; US-PPGPUB; EPO; JPO USPAT; US-PPGPUB; EPO; JPO	2004/06/04 18:44
4	75	semiconductor with thinned same bump\$	USPAT; US-PPGPUB; EPO; JPO USPAT; US-PPGPUB; EPO; JPO	2004/06/04 18:45